## WE CLAIM:

- 1. A non-magnetic physical vapor deposition target consisting essentially of Co, silicon, and one phase.
- 2. The physical vapor deposition target of claim 1 consisting of the Co, silicon and one phase.
- 3. The physical vapor deposition target of claim 1 comprising a density that is at least 85% of a theoretical maximum density of the material of the target.
- 4. A non-magnetic physical vapor deposition target consisting essentially of Ni, silicon, and one phase.
- 5. The physical vapor deposition target of claim 4 consisting of the Ni, silicon and one phase.
- 6. The physical vapor deposition target of claim 4 comprising a density that is at least 85% of a theoretical maximum density of the material of the target.

7. A physical vapor deposition target, comprising:

at least 30 atom percent cobalt;

at least 10 atom percent silicon; and

one phase comprising cobalt, and not more than 1% of any additional phases comprising cobalt other than said one phase.

- 8. The physical vapor deposition target of claim 7, wherein the target is non-magnetic.
- 9. The physical vapor deposition target of claim 7, wherein the target comprises no more than 1% of any additional phases which do not comprise cobalt.
- 10. The physical vapor deposition target of claim 7 comprising a density that is at least 85% of a theoretical maximum density of the material of the target.
- 11. The physical vapor deposition target of claim 7 comprising a density that is at least 90% of a theoretical maximum density of the material of the target.
- 12. The physical vapor deposition target of claim 7 comprising a density that is at least 93% of a theoretical maximum density of the material of the target.

- 13. The physical vapor deposition target of claim 7 consisting essentially of the cobalt and silicon.
- 14. The physical vapor deposition target of claim 7 consisting of the cobalt and silicon.
- 15. The physical vapor deposition target of claim 7 consisting essentially of CoSi<sub>2</sub>.
- 16. A physical vapor deposition target, comprising: at least 30 atom percent nickel; at least 10 atom percent silicon; and one phase comprising nickel, and not more than 1% of any additional phases comprising nickel other than said one phase.
- 17. The physical vapor deposition target of claim 16 comprising a density that is at least 85% of a theoretical maximum density of the material of the target.

- 18. The physical vapor deposition target of claim 16 wherein the target comprises less than 1% of any additional phases which do not comprise nickel.
- 19. The physical vapor deposition target of claim 16, wherein the target is non-magnetic.
- 20. The physical vapor deposition target of claim 16 consisting essentially of the Ni and silicon.
- 21. The physical vapor deposition target of claim 16 consisting of the Ni and silicon.
  - 22. A physical vapor deposition target, comprising: at least 30 atom percent total of one or more of Co, Ni, Ta, Ti, Pt, Mo; at least 10 atom percent silicon;

one phase comprising the one or more of Co, Ni, Ta, Ti, Pt, and Mo and not more than 1% of any additional phases comprising the one or more of Co, Ni, Ta, Ti, Pt, and Mo other than said one phase; and

wherein the target is non-magnetic.

- 23. The physical vapor deposition target of claim 22 comprising a density that is at least 85% of a theoretical maximum density of the material of the target.
- 24. The physical vapor deposition target of claim 22 wherein the target comprises no more than 1% of any additional phases which do not comprise one or more of Co, Ni, Ta, Ti, Pt and Mo.
- 25. The physical vapor deposition target of claim 22 comprising at least 30 atom percent of Ta.
- 26. The physical vapor deposition target of claim 22 comprising at least 30 atom percent of Ti.
- 27. The physical vapor deposition target of claim 22 comprising at least 30 atom percent of Pt.
- 28. The physical vapor deposition target of claim 22 comprising at least 30 atom percent of Mo.

29. A physical vapor deposition target, comprising:

at least 20 atom percent total of W;

at least 10 atom percent silicon;

one phase comprising WSi<sub>2</sub> and not more than 1% of any additional phases other than said one phase; and

wherein the target is non-magnetic.

30. The target of claim 29 wherein the W concentration is at least 25 atom percent.